

# 100% Material Declaration Data Sheet FGG676 Package for Spartan-6 FPGAs

**Average Weight: 2.981g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.090946</b>	<b>3.051</b>
	Silicon	7440-21-3	100.00		0.090946	
<b>Die Attach Material</b>					<b>0.016016</b>	<b>0.537</b>
	Silver	7440-22-4	77.50		0.012412	
	Bismaleimide Monomer	Trade Secret	15.00		0.002402	
	Acrylate Monomer	Trade Secret	7.50		0.001201	
<b>Mold Compound</b>					<b>1.371554</b>	<b>46.010</b>
	Solid Epoxy Resin	Trade Secret	11.00		0.150871	
	Phenol Resin	Trade Secret	11.00		0.150871	
	Fused Silica	60676-86-0	62.40		0.855850	
	Metal Hydroxide	Trade Secret	15.05		0.206419	
	Carbon Black	1333-86-4	0.55		0.007544	
<b>Gold Wire</b>					<b>0.015517</b>	<b>0.521</b>
	Gold	7440-57-5	99.05		0.015369	
	Palladium	7440-05-3	0.95		0.000147	
	Calcium	7440-70-2	0.00		0.000000	
<b>Solder Balls</b>					<b>0.564707</b>	<b>18.944</b>
	Tin	7440-31-5	96.50		0.544942	
	Silver	7440-22-4	3.00		0.016941	
	Copper	7440-50-8	0.50		0.002824	
<b>Substrate</b>					<b>0.922260</b>	<b>30.938</b>
	Copper	7440-50-8	33.29		0.307002	
	Nickel	7440-02-0	4.84		0.044637	
	Gold	7440-57-5	0.35		0.003228	
	Fiberglass	65997-17-3	17.24		0.158998	
	Non-Halogen FR	NA	0.01		0.000111	
	BT (Core)	NA	36.13		0.333213	
	Solder Mask	NA	8.14		0.075072	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/28/10	1.0	Initial Xilinx release.

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